

PRODUCT OVERVIEW

WACKER's ELASTOSIL® and SEMICOSIL® thermally conductive silicone products provide efficient and reliable thermal heat control in many different applications. We offer silicone-based products in a variety of viscosities, curing speeds and thermal conductivities to meet requirements for thermal heat management in virtually every industry.

Key Features

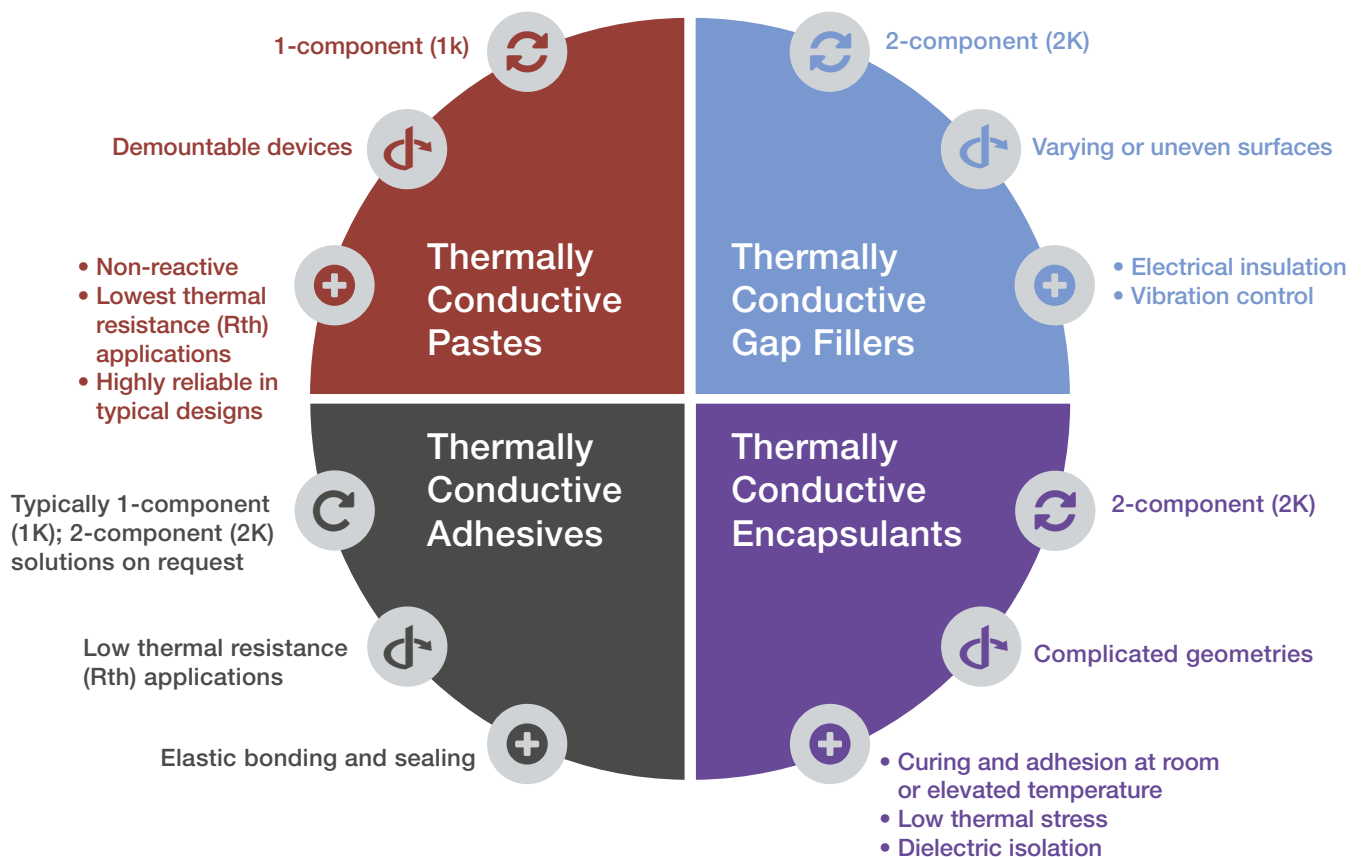
- Soft, flexible gap filling between uneven surfaces
- Thermal conductivity: 2 to 7 W/mK, more in development
- Remains soft and tacky between -50 °C to +180 °C
- Low volatiles, D4-D8 < 350 ppm, UL94-V0
- Room-temperature-curing and heat-curing grades available
- Low-density grades available
- Processing approved by leading equipment manufacturer

Packaging

- Cartridges
- 30 L pails
- 200 L drums

Typical Industries

- Power electronics
- Automotive (electronics) e.g. ECU, ADAS, Sensors



Thermally Conductive Gap Fillers	Thermal Conductivity [W/mK]	Type	Density [g/cm ³]	Viscosity D=10 1/s [mPa-s]	Hardness, Shore 00	Curing [h] at 23 °C	Special Features
SEMICOSIL® 961 TC	2.3	2-part, 1:1	2.9	130,000	25	4–6	GEN1: sedimentation-free, easy to process
SEMICOSIL® 962 TC	3.0	2-part, 1:1	3.1	150,000	50	4–6	GEN1: sedimentation-free, easy to process
SEMICOSIL® 966x TC series	3.0	2-part, 1:1	2.6	<200,000	n.a.	>24	Next-generation, injectible gapfiller
SEMICOSIL® 9671 TC4	2.3	2-part, 1:1	2.1	200,000	60–70	12	Next-generation, low-density, shear thinning
SEMICOSIL® 9673 TC	3.6	2-part, 1:1	2.75	600,000	65	12	Next-generation, low-density, shear thinning
SEMICOSIL® 937 TC (KR)	7.4	2-part, 1:1	3.3	180,000	65	12	High TC gapfiller for ADAS applications

Thermally Conductive Encapsulants	Thermal Conductivity [W/mK]	Type	Density [g/cm ³]	Viscosity D=10 1/s [mPa-s]	Shore	Curing [h] at 23 °C	Special Features
ELASTOSIL® RT 7331 TC (KR)	3.0	2-part, 1:1	2.9	13,000	45 (00)	1 /120 °C	Low-viscosity, self-leveling encapsulant, self-adhesive
ELASTOSIL® RT 739 TC (KR)	2.0	2-part, 1:1	2.7	7,000	40 (A)	1 /120 °C	Low-viscosity, self-leveling, self-adhesive, addition-curing encapsulant
ELASTOSIL® RT 7612 AD TC	1.3	2-part, 1:1	2.4	2,500	60 (00)	2/25 °C	Room-temperature-curing, self-adhesive
ELASTOSIL® RT 7620 TC CN	2.0	2-part, 1:1	2.6	7,000	50 (00)	0.5/80 °C	Low-viscosity encapsulant
ELASTOSIL® RT 7640 TC CN*	4.0	2-part, 1:1	2.8	13,000	55 (00)	N/A	High-TC encapsulant

Thermally Conductive Adhesives	Thermal Conductivity [W/mK]	Type	Density [g/cm ³]	Viscosity D=10 1/s [mPa-s]	Hardness, Shore A	Tensile Strength [mPa-s]	Special Features
SEMICOSIL® 971 TC*	2	1-part	2.7	100,000	80	5	Only in cartridges, re-homogenization necessary

Thermally Conductive Pastes & Greases	Thermal Conductivity [W/mK]	Type	Density [g/cm ³]	Viscosity D=10 1/s [mPa-s]	Curing [h] at 23 °C	Special Features
WACKER® Paste P12	0.81	1-part	2.1	Pasty	Non-curing	Electrically insulating heat paste
SEMICOSIL® Paste 40 TC	4.0	1-part	3.27	250,000	Non-curing	Exceptional thermal conductivity of 4.0 W/mK; low BLT of 60 µm

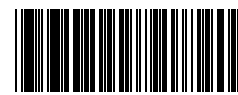
*only upon request and reasonable volumes



Wacker Chemie AG, 81671 Munich, Germany, www.wacker.com/contact, www.wacker.com

Follow us on:

The data presented in this medium are in accordance with the present state of our knowledge but do not absolve the user from carefully checking all supplies immediately on receipt. We reserve the right to alter product constants within the scope of technical progress or new developments. The recommendations made in this medium should be checked by preliminary trials because of conditions during processing over which we have no control, especially where other companies' raw materials are also being used. The information provided by us does not absolve the user from the obligation of investigating the possibility of infringement of third parties' rights and, if necessary, clarifying the position. Recommendations for use do not constitute a warranty, either express or implied, of the fitness or suitability of the product for a particular purpose.



7935en